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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Ligang Zhang, et al.

Title: ELECTROMAGNETIC SHIELDING STRUCTURE

Application No.: 10/813,886

Filed:

March 31, 2004

Examiner: Jennifer E. Matisiak

Group Art Unit:

2811

Atty. Docket No.: 026-0047

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September 23, 2005

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37 C.F.R. § 1.97(b)

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- ☐ Listing of Pending Applications (N/A page(s), with copy of no application(s)).
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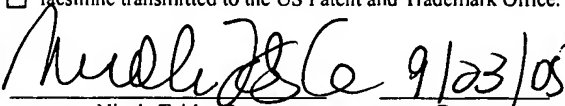
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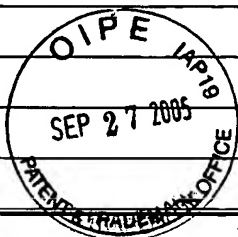
Respectfully submitted,



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| | | Application No.: 10/813,886 |
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| | | Filing Date: March 31, 2004 |
| | | Group Art Unit: 2811 |
| | | Examiner Name: Jennifer E. Matisiak |
| Sheet 1 of 1 | | Date Submitted: September 23, 2005 |



NON PATENT LITERATURE DOCUMENTS

| Examiner Initials* | Cite No. ¹ | Include name of author (in CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. | T ² |
|--------------------|-----------------------|---|----------------|
| | AA | FROMMBERGER, Michael, et al., "Integration of Crossed Anisotropy Magnetic Core Into Toroidal Thin-Film Inductors," IEEE Transactions on Microwave Theory and Techniques, Vol. 53, No. 6, June 2005, pp. 2096-2100. | |
| | AB | KIM, Sung-Jin, et al., "Realization of High-Q Inductors Using Wirebonding Technology," School of Electronics Engineering, Ajou University, AP-ASIG Proceedings, August 1999, 4 pages. | |
| | AC | LONG, John R. and Miles A. Copeland, "The Modeling, Characterization, and Design of Monolithic Inductors for Silicon RF IC's," IEEE Journal of Solid-State Circuits, Vol. 32, No. 3, March 1997, pp. 357-369. | |
| | AD | SOH, H. T., et al., "Through-Wafer Vias (TWV) and their Applications in 3 Dimensional Structures," Proceedings of 1998 International Conference on Solid State Devices and Materials, September 1998, 12 pages. | |
| | AE | TANG, Chih-Chun, et al., "Miniature 3-D Inductors in Standard CMOS Process," IEEE Journal of Solid-State Circuits, Vol. 37, No. 4, April 2002, pp. 471-480. | |
| | AF | TRELEAVEN, Dave and Dick James, "Integrated Circuit Passive Components," Whitepapers, Chipworks, www.chipworks.com/resources/resources_whitepapers.asp , 4 pages. | |
| | AG | TSUI, Hau-Yiu and Jack Lau, 2003 IEEE MTT-S Digest, pp. 225-228. | |
| | AH | WU, Joyce H., et al., "A Through-Wafer Interconnect in Silicon for RFICs," IEEE Transactions on Electron Devices, Vol. 51, No. 11, November 2004, pp. 1765-1771. | |
| | AI | ZANNOTH, Markus, et al., "A Fully Integrated VCO at 2 GHz," IEEE Journal of Solid-State Circuits, Vol. 33, No. 12, December 1998, pp. 1987-1991. | |
| | AJ | ZOU, Jun, et al., "Development of Vertical Planar Coil Inductors Using Plastic Deformation Magnetic Assembly (PDMA), 2001 IEEE International Microwave Symposium, May 2001, 4 pages. | |
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